

1 Deep Underground Neutrino Experiment (DUNE)

2 Technical Proposal

3 **23 Feb 2018: First draft of the TP volumes due**

4 Volume 3: *The Dual-Phase Far Detector*

5 February 22, 2018

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1 **Todo list**

- 2 update figure with only two curves for -162 and 27 C 7
- 3 update figure with only two curves for -162 and 27 C 7

Chapter 1

TPC Electronics

1.1 TPC Electronics System Overview

1.1.1 Introduction

The aim of the DP TPC electronics is to collect and digitize the signals from the Charge Readout Plane (CRP) and photon detectors, Photo-Multiplier Tubes (PMT), in the Dual-Phase (DP) detector module. The design of the system relies on the components already developed for the ProtoDUNE-DP detector as a result of an R&D activity started in 2006. One of the key objectives of this R&D program has been the design of the electronics system that is easily scalable, and cost-effective in order to meet the needs of the large-scale neutrino liquid argon detectors.

While a single DP detector module has a factor of 20 more readout (both charge and light) channels than ProtoDUNE-DP, a simple scaling of the number of the components used in the prototype is sufficient to meet the overall system requirements. A small-scale version of the TPC electronics system has been used in a dual-phase LAr TPC prototype, LArProto, at CERN with an active volume (CRP area) of $3 \times 1 \times 1 \text{ m}^3$ ($3 \times 1 \text{ m}^2$) that took data in the Summer-Fall 2016. The experience gained from the LArProto operation allowed to validate already some of the design choices and check various performance markers (e.g., noise).

The Charge ReadOut (CRO) system is designed to provide continuous, non-zero-suppressed, and losslessly compressed digital signals by reading the charge collected on the 3 m long strips arranged in two collection views with a pitch of 3.125 mm in the CRP. The system consists of a Front-End (FE) analog electronics operating at cryogenic temperatures and digital electronics working in the warm environment outside of the cryostat. The cryogenic FE analog electronics is based on an ASIC chip with a large dynamic range (up to 1200 fC) to cope with the charge amplification in CRP. The analog FE cards are housed in dedicated Signal FeedThrough (SFT) chimneys and are accessible from the outside even after the detector module is in operation thus removing any significant risks associated with their long-term survivability. The SFT chimneys are approximately 2 m long objects that traverse the entire insulation layer of the cryostat allowing to place the FE electronics

1 close to the CRP to minimize cable capacitance (noise). In addition, their metallic structure
2 shield the FE cards from any interference from the digital electronics and ambient environment.
3 The analog signals are digitized by Advanced Mezzanine Cards (AMC), which are housed in the
4 commercial uTCA crates on top of the cryostat near the SFT chimneys. The data are sampled
5 at the rate of 2.5 MHz with 12 bit resolution. This frequency, traditionally used in LAr TPC
6 experiments, matches well the 1 μ s pulse-shaping time of FE electronics and the detector response
7 times determined by the electron drift velocity in the liquid argon. The corresponding sampling
8 resolution along the drift coordinate is better than 1 mm.

9 The Light ReadOut (LRO) electronics collects and digitizes the signals from the photon-detector
10 system, which consists of TPB-coated 8 inch photomultiplier tubes (Hamamatsu R5912-02-mod)
11 located under the TPC cathode. The LRO electronics should facilitate the detection of the primary
12 scintillation signals, which provide the absolute time reference for the interaction events. It should
13 also enable recording the light signals generated by photons from so-called proportional scintillation
14 component, the light created by the electrons extracted and amplified in the gaseous phase. The
15 electronics, consisting of analog and digital stages, is housed in the uTCA crates on top of the
16 cryostat structure.

17 Each uTCA crate for either charge or light readout is connected to the DAQ system via an optical
18 fiber link, which support the speed of at least 10 Gbit/s. Every crate also contains a module
19 (WR-MCH) for the time synchronization of the digital electronics. This timing slave unit is
20 connected via 1 Gbit/s optical fiber to a master node that serves as a synchronization reference for
21 all the connected slave nodes on the network. This system for the time synchronization is based
22 on the commercially available components developed within the framework of the White Rabbit
23 (WR) project. The system performs automatic and continuous self-calibrations to account for any
24 propagation delays and is able to provide sub-ns accuracy for the timing synchronization.

25 1.1.2 Design Considerations

26 The design of the electronics for the charge readout covers the analog front-end cards containing
27 pre-amplifier ASICs operating at cryogenic temperatures and digitization cards with the relevant
28 system for their synchronization working in the warm environment outside of the cryostat. The
29 principle requirements for the system is to read and digitize signals from a total of 153,600 channels
30 (per one DP detector module) and be capable of continuously streaming the collected and losslessly
31 compressed data to DAQ without any zero suppression. Given the amplification of the ionization
32 charge in CRP, the electronics needs to be sensitive to the signals over a large dynamic range
33 (up-to 40 times the MIP-level signals for a nominal CRP gain of 20) to avoid saturation of the
34 analog inputs by large localized energy disposition produced, for example, in hadronic shower
35 events. The charge amplification provided by the CRP loosens requirements on the intrinsic noise
36 of the FE analog electronics. For the CRP nominal gain of 20, the signal-to-noise ratio for a
37 MIP signal (30 fC) should be at least around 100, which would not pose any problems for the
38 detection/reconstruction. The magnitude of noise, however, plays a role in the quality of the
39 lossless compression on the raw data performed by the digital electronics. A compression factor of
40 10 can be achieved with the noise levels below 1 ADC RMS.

1 The primary objective of the light readout system is to detect signals, from a minimum of one
 2 photo-electron on one PMT, giving a precise timestamp that can be used in conjunction with
 3 the charge signals to determine the time (drift) co-ordinate of an event. Precise measurements
 4 of signal charge will allow the continual monitoring of the PMT gain at the single photo-electron
 5 level, and the determination of the number of photons in each scintillation event. In addition,
 6 an ADC will continuously stream data, downsampled to 400 ns as for the CRO signals, which,
 7 amongst other items, will allow measurements of the scintillation time-profile. In addition, the
 8 light readout system will sample a small number of signals from the PhotoDetection calibration
 9 system: the calibration trigger and around 20 channels from reference sensors.

10 The cryogenic analog electronics for charge readout is housed in dedicated SFT chimneys. Their
 11 design must enable access to the FE card for possible replacement without any risk of contaminating
 12 the pure liquid argon in the main cryostat volume. The chimneys must possess a cooling system
 13 that would permit to control the temperature around the FE cards around 110 K for their optimal
 14 noise. In addition, the cooling system is to compensate for the heat input from the chimneys into
 15 the cryostat volume.

16 The digital electronics for both charge and light readout is located in the warm environment on
 17 the top of the cryostat supporting structure and is therefore easily accessible. This fact removes
 18 any constraints associated with the accessibility and operation in cryogenic environments allowing
 19 for the usage of standard components and industrial solutions in the design. Digital electronics
 20 must be continuously and automatically synchronized to better than 400 ns to ensure the correct
 21 temporal alignment of the ADC samples from all of the readout channels. This is a minimal
 22 requirement dictated by the fact that the sampling rate is 2.5 MHz.

Table 1.1: Parameters for the TPC electronics system design. The numbers are given for one detector module.

Parameter	Value
CRO channels	153,600
CRO continuous sampling rate	2.5 MHz
CRO ADC resolution	12 bit
CRO data compression factor	10
CRO data flow	430 Gbit/s
LRO channels	720
LRO continuous sampling rate	2.5 MHz
LRO ADC resolution	14 bit
LRO data compression factor	1
LRO data flow	24 Gbit/s

23 Some of the key parameters in the electronics system design are summarized in Table 1.1. The
 24 requirements for the DP electronics system are documented in DUNE-docdb-6428.

1.1.3 Scope

The scope of the TPC electronics system covers the procurement and productions, testing and validation, installation, and commissioning of all the components necessary to ensure the complete readout of the charge and light signals from a given DP detector module. The covered items are the following:

- Cryogenic analog FE cards for charge readout
- AMC cards for charge/light readout
- The WR-MCH cards for AMC clock synchronization
- uTCA crates
- Switches for the White Rabbit network
- SFT chimneys
- Low-voltage power supplies for the FE cards
- Flat cables connecting the FE cards to the warm flange interface of the SFT chimneys
- VHDCI cables connecting the warm flange interface of the SFT chimneys to AMCs

The total numbers for components to be procured to instrument one detector module are given in Table reftab:dpele-num-components

Table 1.2: Numbers for DP electronics components to procure for one detector module

Name	Number
CRO cryogenic ASICs (16 ch)	9600
CRO cryogenic analog FE cards (64 ch)	2400
CRO AMCs	2400
SFT chimneys	240
Flat cables for SFT chimney (68 ch)	2400
Flat cables for SFT chimney (80 ch)	2400
VHDCI cables (32 ch)	4800
LRO AMCs with analog FE	45
uTCA crates	245
WR-MCH units	245
WR switches (18 ports)	16

1.2 TPC Electronics System Design

1

c-design

2 The CRO FE analog electronics is based on cryogenic ASIC chip with a large dynamic range (up
3 to 1200 fC) to accommodate the charge amplification in the dual-phase CRP. The FE cards read 64
4 CRP channels each. They are mounted in dedicated Signal FeedThrough (SFT) chimneys and are
5 located within a short distance (<1 m) from each CRP to minimize the noise caused by long cables
6 (large cable capacitance). The cards remain accessible throughout the detector operation. Each
7 SFT chimney hosts 10 FE analog cards, which corresponds to the readout of 640 CRP channels
8 per chimney. There are, therefore, 240 SFT chimneys to be installed for the charge readout in a
9 given DP detector module.

10 The differential analog signals from the analog FE cards, routed via an interface flange of the SFT
11 chimneys, are digitized by AMC cards located in the warm conditions outside of the cryostat.
12 AMCs are hosted in uTCA crates. In the baseline version of the design (utilized currently in
13 ProtoDUNE-DP), each AMC digitizes 64 channels corresponding to reading one FE analog card.
14 Each uTCA in such case contains 10 AMCs (640 channel). However, an implementation with
15 AMCs supporting a higher channel density is also being investigated for cost reduction purposes.
16 A given SFT chimney is serviced by one uTCA crate placed in its immediate vicinity.

17 The LRO FE analog and digital electronics is based on a custom-built AMC. The card contains
18 a CATIROC ASIC, which is used to determine precisely the charge and start times of signals
19 from each individual PMT. In addition, a 14 bit 65 MHz ADC digitizes the data for continuous
20 streaming of the PMT signals. Each card can read up to 16 channels. A potential future upgrade
21 is to increase the channel density per card to 32 channels. The LRO cards are housed in five
22 dedicated uTCA crates located close to the PMT instrumentation feedthroughs.

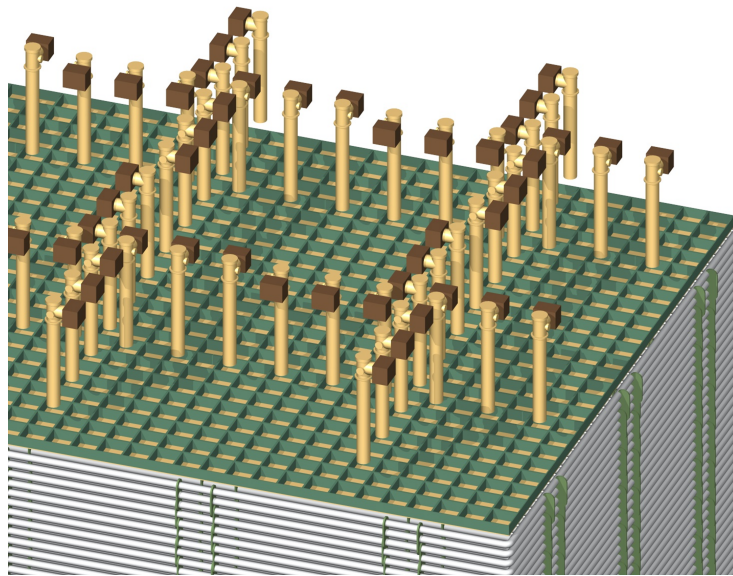


Figure 1.1: Corner view of DP detector module showing the pattern of the SFT chimneys and uTCA crates for charge readout above CRPs

fig:dpe1

23 Every uTCA crates contains a network switch, MicroTCA Carrier Hub (MCH), via which the

1 data are sent to DAQ as well as a module (WR-MCH) for clock/time synchronization and trigger
 2 timestamp distribution to the AMCs. Both MCH and WR-MCH require one optical fiber link
 3 each.

4 The MCH switch streams the data from AMCs via a dedicated optical link. Currently ProtoDUNE-
 5 DP uses MCH operating at 10 Gbit/s. However, a move to 40 Gbit/s links for the DUNE FD
 6 implementation is considered because of the technology evolution and possible increase in the
 7 channel density of each AMC.

8 The WR-MCH time synchronization unit is based White Rabbit (WR) system, which provides
 9 hardware and protocols for the network-based sub-ns synchronization between a master and differ-
 10 ent slave nodes. The connection of the WR-MCH to the White Rabbit network is done via 1 Gbit/s
 11 optical link. WR-MCH distributes the timing information for synchronization of the AMCs via
 12 the uTCA backplane. In addition, this unit can be used to transmit triggers to the digitization
 13 units within the crate. This is achieved by sending it dedicated data packets containing trigger
 14 timestamp information.

15 Figure [1.1](#) shows a corner view of the DP detector module illustrating the pattern of the SFT
 16 chimneys and the attached uTCA crates above the CRPs. Each crate/SFT chimney collects
 17 signals from 3 m long strips of two $1 \times 3 \text{ m}^2$ CRP segments. Each chimney completely traverses
 18 the insulation layers (not shown in the figure).

Table 1.3: Summary of some of the principal numbers of the TPC electronics system for charge and light readout of a detector module

Name	Number
CRO SFT chimneys/uTCA crates	240
CRO channels per SFT chimney/uTCA crate	640
CRO cryogenic analog FE cards per SFT chimney	10
CRO AMCs per uTCA crate	10
LRO FE cards per uTCA crate	9
LRO channels per uTCA crate	144
LRO uTCA crate	5
WR-MCH per uTCA crate	1

19 A short summary of some of the number of principal components and channel granularity in the
 20 design of the DP electronics is provided in Table [1.3](#).

21 1.2.1 Cryogenic Analog FE Electronics

22 The cryogenic amplifier ASIC is the main component of the FE analog cards. Its design is based
 23 on the CMOS $0.35 \mu\text{m}$ technology and is an outcome of an R&D activity started in 2006. Two
 24 principal version of ASIC chips have been produced for the dual-phase LArTPC operation. In the
 25 first version the amplifiers have a constant gain in the region of $0 - 1200 \text{ fC}$ ($0 - 40 \text{ MIP}$). In the

second, the amplifiers have a higher linear gain for signals up to 400 fC (roughly 10 MIP signals) and a logarithmic response in the 400 – 1200 fC range. This double-slope behavior is obtained by using a MOSCAP capacitor in the feedback loop of the amplifier that changes its capacitance above a certain signal threshold. The aim of this solution is to optimize the resolution for small charge depositions (in a few MIP region) while preserving overall the large dynamic range of the amplifier.

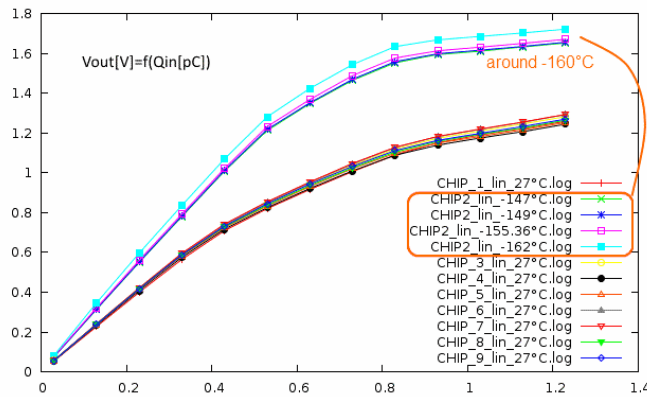


Figure 1.2: Gain response of the cryogenic FE ASIC

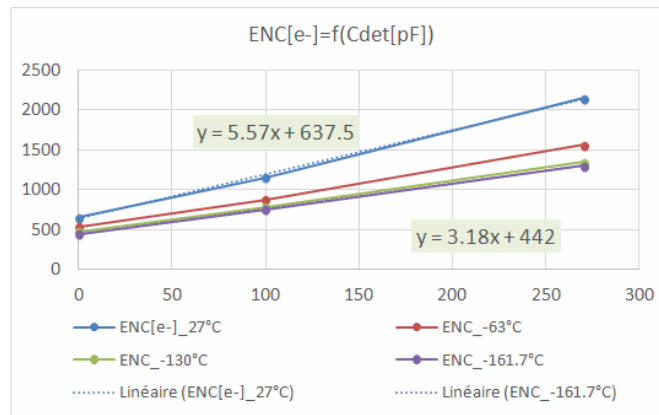


Figure 1.3: Noise of the cryogenic FE ASIC as a function of the detector capacitance

The ASIC version with the double-slope gain has been selected for ProtoDUNE-DP and adopted in the DP TPC electronics design. Figure 1.2 illustrates the response of the amplifier as a function of the injected charge for this chip, while Figure 1.3 shows the measured noise in units of Equivalent Noise Charge (ENC) as a function of the ("detector") capacitance at different temperatures. The ASIC contains 16 amplifier channels with differential line buffers and has a power consumption which is <18 mW per channel.

Each cryogenic FE card, shown in Figure 1.4, hosts four ASIC amplifier chips and a few passive discrete components. The input stage of each amplifier channel has a 1 GΩ resistor to ground

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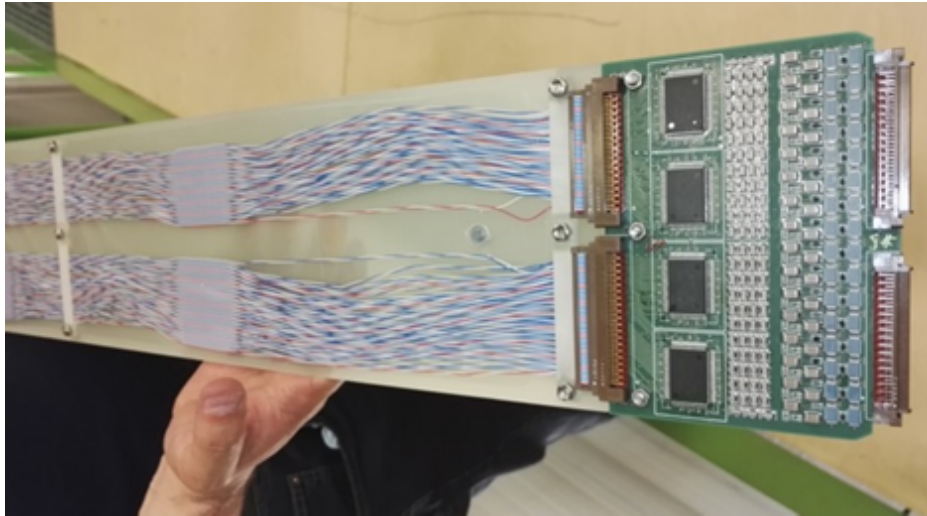


Figure 1.4: Image of an analog cryogenic FE card mounted on the extraction blade

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1 followed by a 2.2 nF decoupling capacitor. The function of the resistor is to provide the ground
 2 reference for the anode strips of CRP. Each input stage is protected against discharges coming from
 3 the detector with a TVS diode (Bourns CDSOD323-T08LC). This component was selected after
 4 studying the performance of different ESD components subjected systematically to discharges of
 5 a few kV with an energy similar to that of LEMs in CRP. The FE cards also house the blocking
 6 capacitors for filtering the low voltage power lines.

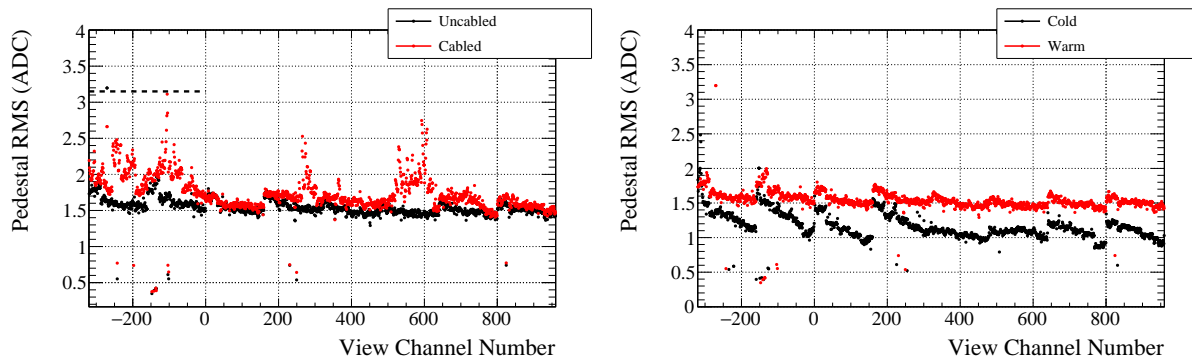


Figure 1.5: Noise of measurements in LArProto in different conditions. Left: at warm with the slow control cables connected to the cryostat flanges (red points) and disconnected (black points). Right: at warm (red points) and cold (black points) with the slow control cables disconnected. The channels with negative (positive) channel number correspond to the strips of 3 m (1 m)

fig:dpele

7 While the FE amplifier ASICs are in the shielded environment provided by the chimneys (Faraday
 8 cage), interference from other equipment via a noisy ground or ground loops could significantly
 9 worsen the noise performance from the design target. Figure 1.5 shows some results of the noise
 10 measurements performed under different conditions in the LArProto detector. The channels read-
 11 ing 3 m (1 m) long strip correspond to negative (positive) channel numbering in the plots and the
 12 1 ADC count is equivalent to about 900 electrons. The left plot of Figure 1.5 shows the noise
 13 measurements performed at warm with and without slow control cables (CRP HV, CRP motors,
 14 level meters, temperature probes, etc.) connected. The noise is clearly affected by the grounding
 15 of the slow control: the average value of the noise RMS is around 1.7 ADC with slow control

1 cables connected and decreases to about 1.5 ADC when those are removed. One interesting fea-
2 ture, particularly visible with the cables disconnected, is that the noise measured in LArProto is
3 similar for the channels connected to the 1 m and 3 m long strips. Given that the longer strips
4 have thrice the input capacitance than the shorter ones, the expected noise (see Figure 1.3) for
5 these should be larger by a factor of 2 as indicated by the dashed line in the plot. In addition,
6 the noise on the short strips is also lower (1.5 ADC) than expected for the 160 pF/m strip input
7 capacitance (1.7 ADC). The reason for such behaviour of the noise in the CRP of LArProto is still
8 under investigation. However, measurements have shown that the capacitance of the CRP anode
9 strips is not purely to ground, but rather it is driven by the inter-strip couplings, which creates a
10 more complicated electrical network.

11 Figure [fig:dpele-311-noise](#) 1.5 (right) also shows a comparison of the noise measurements in LArProto taken with the
12 FE electronics at warm (red points) and cold (black points) at around 150 K. The slow control
13 cables were disconnected in both cases. However, the measurements at cold were performed with
14 the re-circulation pump active and the cathode HV connection present. The RMS noise averaged
15 over all channels decreases by about 25% from roughly 1.5 ADC to 1.1 ADC when the FE analog
16 cards are at cold. For comparison, the expected signal for a MIP with the CRP gain of 20 should
17 be around 200 ADC.

18 The overall grounding principle of LArProto was based on having the cryostat as the ground
19 reference. The low voltage power supplies for the FE analog electronics and uTCA crates were
20 powered via insulating transformers ensuring that they could see no other ground. On the other
21 hand, the design of the slow control system did not include any insulation transformers. This
22 equipment was the grounded to the building electrical network thereby creating an interference
23 with the ground of the cryostat. Stricter treatment of the ground connections to the detector
24 module and a lower SFT chimney operating temperature of around 110 K (from 150 K) should
25 help to reduce further the noise levels from those observed in LArProto.

26 1.2.2 SFT Chimneys

27 The SFT chimneys are designed to enable the access to the FE analog electronics for a potential
28 repair or exchange while the detector is in operation (filled with the liquid argon). In addition, their
29 metallic structure acts as a Faraday cage isolating the FE ASICs from environmental interference.
30 Each SFT hosts 10 analog cryogenic FE cards (reading 640 channels in total). Some of the details
31 of the design are illustrated in Figure [fig:dpele-sft-chimney-design](#) 1.6.

32 The chimneys are closed at the bottom and top with vacuum tight flanges whose function is
33 to dispatch the signal and slow control lines. The flange at the bottom, the cold flange, isolates
34 (Ultra-High Vacuum tightness standard) the inner volume of the detector module from the chimney
35 volume and interconnects the signals from the CRP to the analog FE cards. The flange at the top,
36 the warm flange, seals the chimney from the outside environment. It also passes the low voltage
37 and control lines to the FE electronics inside and brings out the differential analog signal lines
38 from the FE amplifiers.

39 The SFT chimney volume is filled with nitrogen gas at near atmospheric pressure. The temperature

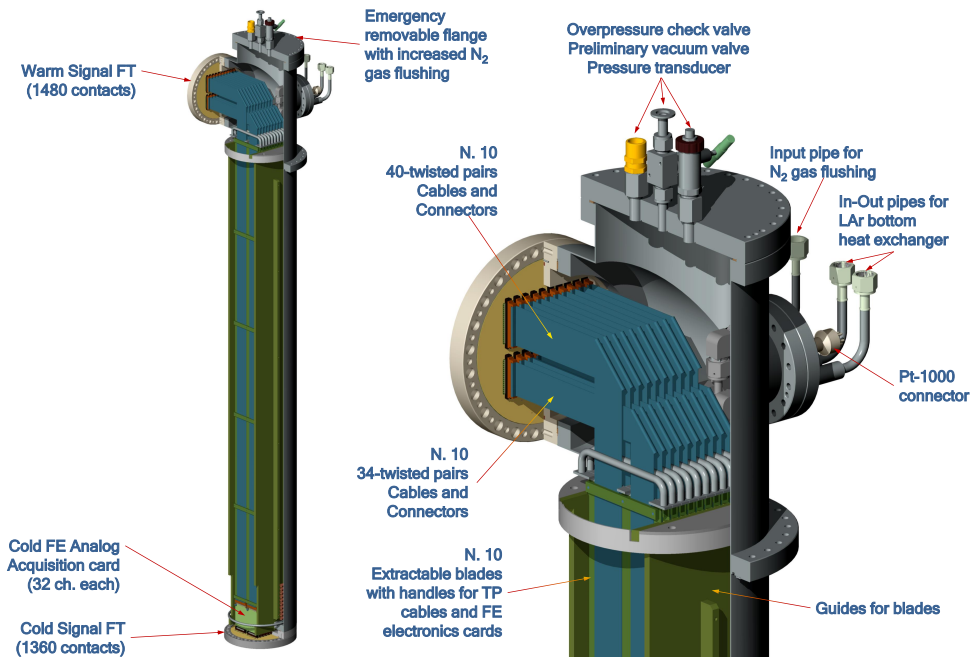


Figure 1.6: Details of the SFT chimney design

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1 inside the chimney can be adjusted using a heat exchanger copper coil cooled with liquid argon.
 2 It is located at the bottom close to the cold flange around the FE cards. The functions of this
 3 cooling system are to mitigate the heat input to the main detector volume and provide optimal
 4 (lowest noise) operating temperature for the FE electronics of around 110K. A pressure release
 5 valve, indicated in Figure 1.6, protects the structure from an accidental overpressure in the inner
 6 volume.

7 The expected heat input from a given SFT chimney is about 20 W. This number includes the heat
 8 through the twisted-pair cables connected to the warm flange, the SFT outer metallic tube, as well
 9 as the heat dissipation by the FE cards. A total heat input from all 240 SFT chimneys is at the
 10 level of 5 kW.

11 The analog FE cards are inserted directly onto the PCB of the cold flange (see Figure 1.7). The
 12 other side of the PCB (facing inside the cryostat) hosts the connectors for the flat cables coming
 13 from the CRP anodes. The FE cards are mounted on 2 m long blades made from FR4, which
 14 enable the insertion/extraction of the electronics and also support the flat cables carrying signals,
 15 low voltages, and slow control to/from the warm flange interface. The blades slide along the
 16 rails installed inside the chimney at opposite sides, which guide the FE cards to their respective
 17 connectors on the cold flange.

18 Prior to the commissioning of a detector module, the chimneys are evacuated via a dedicated KF16
 19 port (see Figure 1.6) and then filled with nitrogen gas. This ensures the removal of the moisture
 20 that would otherwise condense, once the detector module is filled with the liquid argon, around the
 21 FE cards damaging the electronics. To access the FE cards once the detector module is cold, the
 22 stainless steel flange at the top of the SFT chimney (Figure 1.6) must be removed. This procedure
 23 requires continuous flushing of nitrogen gas at slight over-pressure with respect to the atmospheric

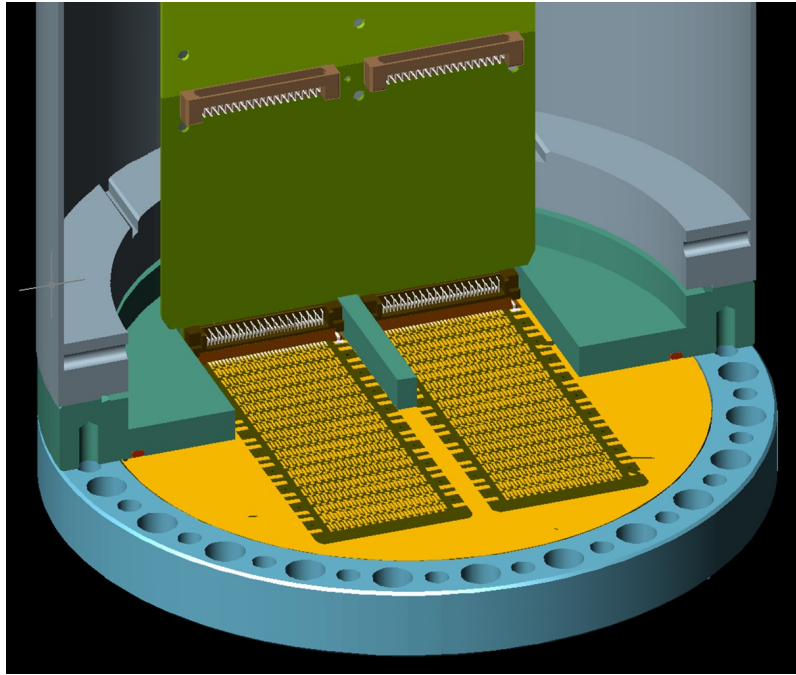


Figure 1.7: SFT chimney cold flange with one of the FE cards mounted

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1 in order to prevent the humid air entering and generating condensation inside the chimney. Once a
 2 chimney is opened, the blades with the FE cards can be extracted after unplugging the flat cables
 3 (two per card) connected on the inner side of the warm flange (Figure 1.6).

4 The procedure to access the FE cards at cold was successfully tested during the operation of
 5 the LArProto detector. The temperature at the top of the chimney was very close to the room
 6 temperature allowing to manipulate the cable connections on warm flange without any cryogenic
 7 gloves. The movement of the blades on the rails and the FE card extraction / insertion did not
 8 indicate any mechanical problems that could have been caused by shrinking of various elements due
 9 to the lower temperatures. The signals from the FE cards that underwent the extraction/insertion
 10 were also checked and no malfunctioning channels were found.

11 1.2.3 Digital AMC Electronics for Charge Readout

12 The function of the CRO AMC cards is to read and digitize the data from the FE amplifier and
 13 then transmit them to the DAQ system. Each card has eight ADC chips (AD9257), two dual-port
 14 memories (IDT70T3339), and an FPGA (ALTERA Cyclone V) on board. The FPGA provides
 15 a virtual processor (NIOS) that handles the readout and the data transmission. The cards also
 16 include a last stage of analog shaping before the ADC input.

17 Figure 1.8 shows block diagram of the AMC functionality. The data are continuously sampled at
 18 2.5 MHz with 14 bit resolution. However only 12 most significant bits of each sample are eventually
 19 sent to the DAQ. Within AMCs lossless data compression based on an optimized version of the
 20 Huffman algorithm is performed and the data are organized in frames for transmission. The frames

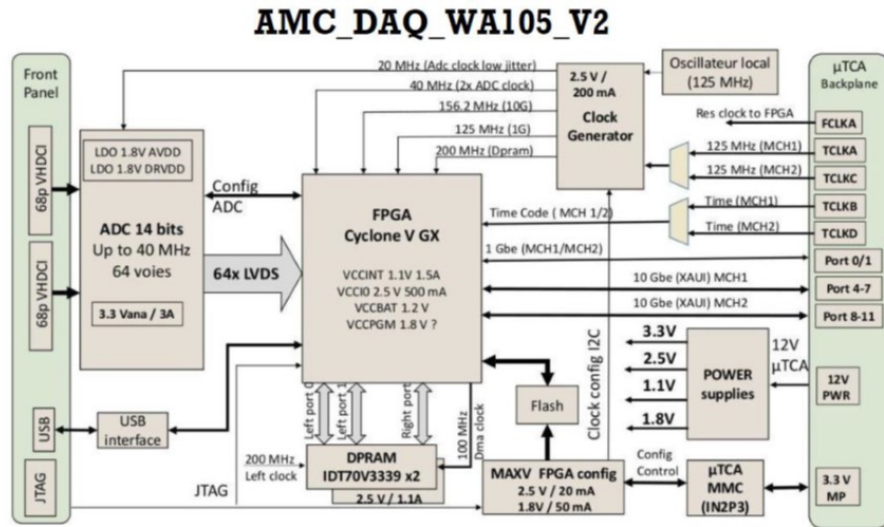


Figure 1.8: Block diagram of AMC

fig:dpele

1 contain the absolute timing information of the first data sample. In the current design, each AMC
 2 has 64 channels and reads one analog FE card.

3 The AMCs are housed in uTCA crates and send their data via the MCH switch. The timing
 4 synchronization of AMCs is achieved via a WR-MCH module (also housed in the crate) that is
 5 connected to the White Rabbit network. In addition, WR-MCH could also be used for triggered
 6 readout of AMCs by sending it dedicated packets containing trigger timestamp information over
 7 the White Rabbit network.

8 In ProtoDUNE-DP, AMCs are operated in the triggered mode reading 4 ms drift time window at
 9 trigger rate of 100 Hz, which is not far from a continuous readout mode. The analog data are
 10 continuously digitized and buffered. A sub-sample of this data can then be acquired by providing
 11 AMC with a timestamp generated by an external trigger. The timestamp defines the start time
 12 for the data sequence to be read, while the length of the sequence is determined by the size of the
 13 drift window. In ProtoDUNE-DP this length corresponds to 10,000 (4 ms) samples per full drift
 14 window. Triggers (beam counters, cosmic ray counters, photomultipliers reading the UV light,
 15 starts of beam spills) are time stamped in a dedicated White Rabbit slave node (WR-TSN), an
 16 FMC-DIO mezzanine mounted on WR SPEC carrier card, which runs a custom firmware and is
 17 hosted in a computer. The WR-TSN is connected to the WR Grand Master for synchronization
 18 and for transmission of the trigger information. The timestamp data produced by the WR-TSN
 19 are sent over the White Rabbit network as Ethernet packets with a customized protocol.

20 1.2.4 Electronics for Light Readout

sign-lro

21 The LRO card is a 16 channel AMC containing one 16 channel 14 bit 65 MHz ADC (AD9249) and
 22 one CatiROC ASIC [?]. A block diagram of the prototype board used for ProtoDUNE-DP is shown
 23 in Figure 1.9. In this prototype, Figure 1.10, a mezzanine board containing the ASIC and ADC

sits on a commercial (COTS) mother board (Bittware S4 AMC) with a high specification FPGA (ALTERA Stratix IV). In the final implementation for the DUNE, the mezzanine is integrated with the layout of the AMC board developed for the charge readout. A proposed upgrade is a 32 channel card, diminishing the number of cards required and increasing the channel density to 352 channels per uTCA crate.

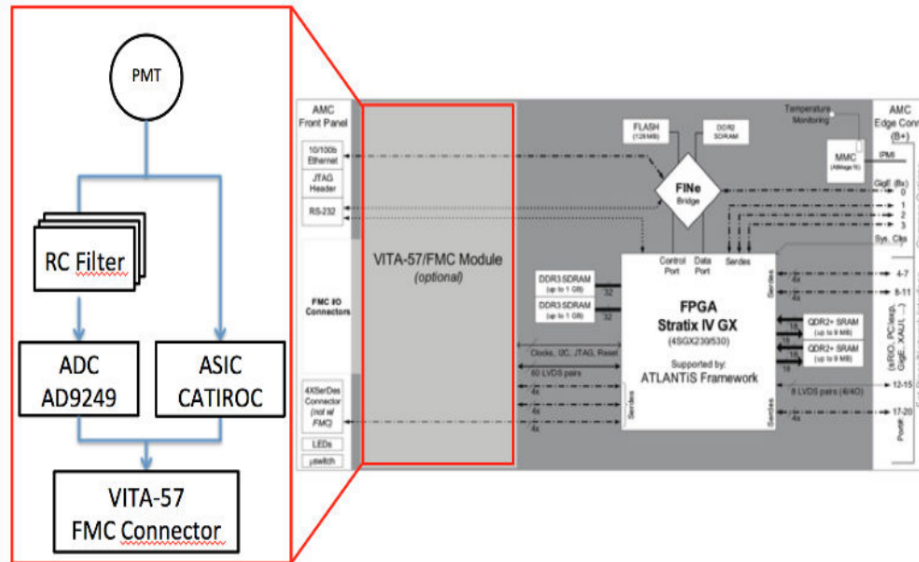


Figure 1.9: Block diagram of LRO prototype.

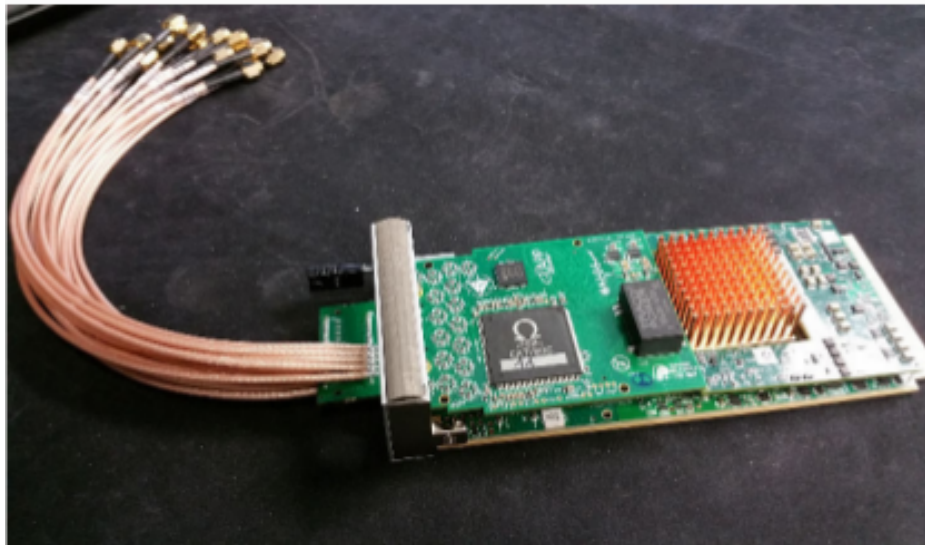


Figure 1.10: The LRO prototype.

The analog signals from each PMT channel follow two separate branches (see Figure 1.9). One path (Waveform branch), through an anti-aliasing low-pass filter and the 14 bit 65 MHz ADC (AD9249), produces continuous digitization of the PMT waveform data, which are down-sampled to 2.5 MHz prior to the transmission to DAQ. The other (CatiROC branch) is routed directly to the CatiROC ASIC for precise measurements of pulse charge and timing. Both paths produce data continuously and independently.

1 Waveform branch

2 The main characteristics of the ADC used for continuous digitization of the PMT signals are shown
3 in Table 1.4.

Table 1.4: Main characteristics of the ADC AD9249

Item	
Time resolution	15 ns
Amplitude resolution (LSB)	0.122 mV
Dynamic range	14 bit/ 2 V
Differential Non-Linearity	Typical ± 0.6 LSB with Min. -0.9 and Max. 1.6 LSB
Integral Non-Linearity	Typical ± 0.9 LSB with Min. -3 and Max. 3 LSB

4 For normal operation, in continuous sampling mode, the time samples will be down-sampled by the
5 FPGA to a coarse 400 ns sampling to match that of the Charge Read Out and limit the quantity
6 of data streamed. Before this downsampling, there is the possibility of online pulse processing
7 within the FPGA, to make continuous measurements such as rise and fall times. Even at the
8 coarse sampling of 400 ns studies of the liquid argon scintillation time-profile are possible (with
9 the long fall timeconstant of ~ 1500 ns) and also matching of the electroluminescence signal (also
10 known as proportional scintillation light) to that of the charge signal. Low light-level signals, such
11 as the single or few photoelectron signals, will show no time structure, but will consist of 1 sample
12 several LSB above the baseline.

13 CatiROC branch

14 The CatiROC is a 16 channel ASIC dedicated to measurement of charge, and precision timing
15 of negative-polarity PMT signals [?]. It auto-triggers on single photo-electrons, and can sustain
16 a high dark rate of up to 20 kHz/channel. Charge measurements can be made over the range of
17 160 fC to 70 pC (corresponding to approximately to a range of 1 - 400 photo-electrons with a PMT
18 gain of 1×10^6). Timing measurements per channel can be made with an accuracy of 200 ps.

19 Figure 1.11 shows the schematic of the CatiROC ASIC. Its main properties are summarized in
20 Table 1.5. The slow channel, from which precision charge and timing measurements are made,
21 is formed by two variable gain (8 bit) amplifiers followed by two variable slow shapers; one High
22 Gain for small signals, and one Low Gain for larger signals, and two Track-and-Hold stages. The
23 slow shaper has a tunable shaping time (up to 100 ns) and a variable gain. If the High Gain is
24 saturated, corresponding to passing a pre-determined threshold common to all 16 channels, the
25 Lower Gain value is chosen. The chosen charge value is converted by an internal 10-bit Wilkinson
26 ADC operating at 160 MHz. This slow channel operates in a ping-pong mode, with two capacitors
27 to store the slow shaper signals, giving an effective buffer of 2 events. If both capacitors are full,
28 a deadtime of 5 μ s arises.

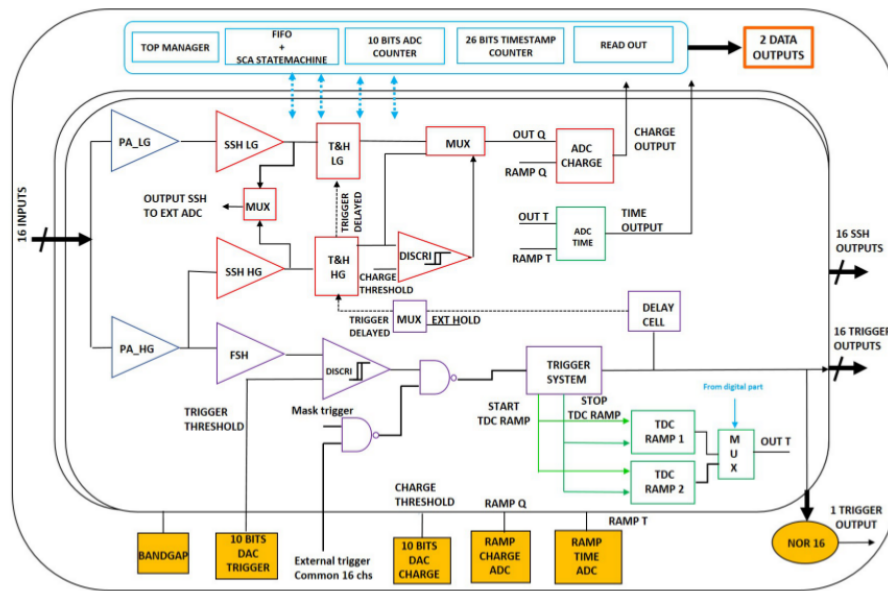


Figure 1.11: Functional diagram of CatiROC ASIC.

fig:dpe1

- 1 The fast channel is used to auto-trigger the ASIC and make the fine-timing measurement. It
- 2 comprises a high gain preamplifier, fast shaper (shaping time 5 ns) and discriminator with a 10 bit
- 3 programmable threshold that is common to all 16 channels. The output of the discriminator is
- 4 used for the two Time to Digital Convertors to get the fine-timing. A coarse timestamp could also
- 5 be obtained from a 26 bit counter running at 40 MHz. Only the data from the triggered channels
- 6 are digitized; their information is transferred to the internal memory, which is read by the external
- 7 FPGA.

1.2.5 Network-based uTCA Architecture

- 9 The digital electronics is based on uTCA standard which offers industrial solution a very compact
- 10 and easily scalable architecture to handle a large number of channels at low cost. The standard
- 11 (or related standards such as ATCA or xTCA) is widely used in the telecommunication industry
- 12 and is being adapted by the HEP community. The backplane of the uTCA crates host high-speed
- 13 serial links that support a variety of transmission protocols (Ethernet, PCI Express, SRIO, etc.).
- 14 In addition, dedicated lanes are available for the distribution of the clock signals to all the boards
- 15 hosted in the crate. The Ethernet-based solution has been adopted for both the data and clock
- 16 distribution in this design of the DP electronics system for both Charge and Light Read Out.

- 17 Each AMC for either charge or light readout plugged into the uTCA is connected to the crate MCH
- 18 board through the backplane serial links. The MCH provides the switch functionality that enables
- 19 AMCs to communicate with each other or external systems through the MCH uplink interface. In
- 20 the DP electronics system design, MCH also manages the WR clock distribution.

- 21 In the current design, as used for ProtoDUNE-DP, the MCH operates with a 10 Gbit/s uplink.
- 22 Given that a uTCA crate hosts 10 AMCs for charge readout, the required bandwidth to stream

Table 1.5: Main characteristics of CatiROC

Item	
Number of channels	16
Signal polarity	negative
Timing	Timestamp: 26 bit counter at 40 MHz Fine time: resolution <200 ps
Charge Dynamic Range	160 fC to 100 pC
Trigger	auto-trigger Noise = 5 fC Minimum threshold = 25 fC (5σ)
Digital	10-bit Wilkinson ADC at 160 MHz Read-out frame of 50 bits
Outputs	16 trigger outputs NOR16 16 slow shaper outputs Charge measurement over 10 bits Time measurements over 10 bits
Main Internal Programmable Features	Variable preamplifier gain Variable shaping and gain Common trigger threshold Common gain threshold

Table 1.6: Bandwidth requirements per uTCA crate for continuous data streaming. A compression factor of 10 for the charger readout data is assumed

Parameter	Value
CRO data rate	1.8 Gbit/s
LRO data rate	4.7 Gbit/s
Current MCH bandwidth	10 Gbit/s
Upgradable MCH bandwidth	40 Gbit/s

1 the data to DAQ is about 1.8 Gbit/s. This assumes that the data exiting the AMC's are losslessly
 2 compressed with the compression factor of 10. The bandwidth required per crate link for streaming
 3 the light readout data is 4.7 Gbit/s. The 10 Gbit/s MCH is therefore sufficient to support these
 4 data rates. However, the technology is moving towards supporting the 40 Gbit/s rates. In addition,
 5 the channel density per AMC could also be increased for cost optimization. For these reasons an
 6 upgrade to a 40 Gbit/s MCH could be foreseen in the future. This would also imply that the optical
 7 links connecting the DAQ system to uTCA MCH should be operable at 40 Gbit/s. A summary of
 8 the required and supported bandwidths per uTCA crate for continuous data streaming is provided
 9 in Table 1.6.

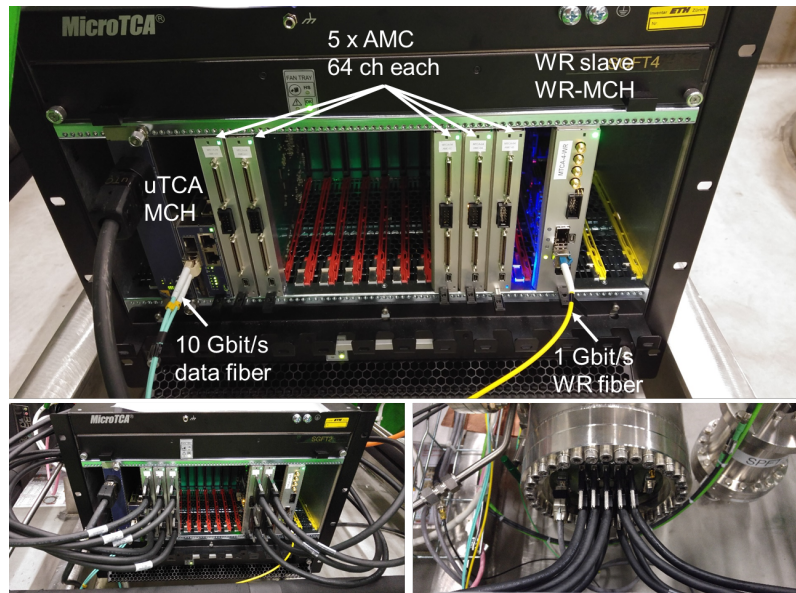


Figure 1.12: Pictures of an instrumented uTCA crate from LArProto detector. The crate contains five AMC cards, correspondingly to the number of readout channels per the SFT chimney. The images below show the crate after the cables are connected to the warm flange of the SFT chimney.

10 As an illustration, Figure 1.12 shows pictures of one of the instrumented uTCA crates used for
 11 the charge readout of LArProto at CERN. In this detector each SFT chimney reads 320 channels
 12 thus requiring only five AMCs per the uTCA crate. The two optical fiber links, one (10 Gbit/s)
 13 for data and the other (1 Gbit/s) for clock/trigger timing distribution, are visible in the images.

14 1.2.6 Timing Distribution

15 The time synchronization system utilizes a White Rabbit (WR) network, which combines the
 16 synchronous 1 Gbit/s Ethernet (SyncE) technology with the exchange of PTPV2 packets, to
 17 synchronize clocks of distant nodes to a common time. A high stability GPS disciplined oscillator
 18 (GPSDO) with the accuracy similar to that of an atomic clock provides a clock reference signal
 19 to be distributed over the physical layer interface of the WR Ethernet network. The network
 20 topology is built using specially designed switches that have the standard IEEE802.1x Ethernet
 21 Bridge functionality with an addition of WR-specific extensions to preserve the clock accuracy.
 22 Time and frequency information are distributed to the nodes on the WR network via optical

1 fibers. The WR protocol automatically performs dynamic self-calibrations to account for any
 2 propagation delays and keeps all connected nodes continuously synchronized to sub-ns precision.

3 The sub-ns accuracy on the clock synchronization is not strictly needed for aligning samples in the
 4 different AMC digitization units, since the data have the timing granularity of 400 ns. However,
 5 WR timing system offers readily available industrial components and necessary protocols needed
 6 for synchronization with automatic calibration of delay propagation and it, therefore, has been
 7 adopted. The necessary R&D for integrating this system with the readout of the ProtoDUNE-DP
 8 detector has been completed.

9 In the implementation specific to ProtoDUNE-DP, a GPS disciplined clock unit (Meinberg LAN-
 10 TIME M600) feeds 10 MHz and 1 PPS reference signals to a commercial White Rabbit switch
 11 (Seven Solutions WRS V3.4). The switch acts as Grand Master of the WR network. It is con-
 12 nected via 1Gbit/s optical links to the dedicated WR timestamping node (WR-TSN) and the WR
 13 end-node slave cards present within each uTCA crate (WR-MCH) keeping these synchronized to
 14 its reference time. The Grand Master also communicates through a standard Ethernet port with
 15 the LANTIME unit for its date and time synchronization via NTP. The WR-TSN module receives
 16 analog TTL-level trigger signals, generates their timestamps, and then transmits these over WR
 17 network to the connected WR-MCH units. This timestamp information is then used by AMCs to
 18 find the data frame corresponding to the trigger.



Figure 1.13: Picture of the WR slave node card (WR-MCH) present in each uTCA crate for time synchronization. The WR-LEN mezzanine card is visible in the bottom right corner

fig:dpele

19 The WR-MCH card (Figure 1.13) enables clock/timing/trigger distribution to AMCs. It com-
 20 municates with them via dedicated lines in the backplane of the uTCA crate using a customized
 21 data-frame protocol. The module contains a commercial WR slave node card, the White Rabbit
 22 Lite Embedded Node (Seven Solutions OEM WR-LEN), as mezzanine card. WR-LEN runs on a
 23 customized firmware which also enables it to decode the trigger timestamp data packet received
 24 over the WR network.

25 The architecture of the WR network layout for one DP detector module is illustrated Figure 1.14.
 26 It is built in a hierarchical structure from 16 WR switches with 18 ports each, chained with
 27 1 Gbit/s optical fibers. The switch at the top of the hierarchy interconnects the synchronization
 28 Grand Master from the DAQ system with the 15 switches in the middle layer. Those are in turn

fig:dpele-wrnet



Figure 1.14: Architecture of WR network for time synchronization of digital readout electronics

fig:dpe1

- 1 connected to the WR-MCH slave nodes in each uTCA crate (245 in total for charge and light
- 2 readout).

3 1.3 Production and Quality Assurance

4 1.3.1 Cryogenic Analog FE Electronics

- 5 The production of the cryogenic ASICs and analog FE cards is envisioned to be split between
- 6 several sites located in France and Japan at the moment. The delivered cards are then split
- 7 between between five institutions in France (IPNL), Japan (KEK, NITKC, IU), and USA (SMU),
- 8 where they are tested.

9 1.3.2 SFT Chimneys

- 10 The production of SFT chimneys consist of manufacturing of the PCB flanges for warm and cold
- 11 flange interfaces, the stainless steel pipe structure and the flanges containing the interfaces to the
- 12 gas/liquid lines and slow control, the blades and railing, and the heat exchanger system. The flat
- 13 cables that connect the FE cards to the warm flange are commercially available products and are
- 14 also procured at this stage.

1 The produced pieces are delivered to one or several institutions participating in the DP electronics
2 consortium. The signal continuity is verified for both cold and warm flanges. The SFT chimneys
3 are then assembled and tested for leaks. The blade insertion is also checked and the flat cables are
4 tested. The assembled SFT chimneys are then packed and shipped to SURF.

5 **1.3.3 Timing System and uTCA**

6 The timing system consisting of 16 WR switches and the 245 uTCA crates containing the power
7 modules, carrier hubs (MCH), and fan units are commercial components. The manufacturer takes
8 the responsibility for the necessary quality control and assurance of these components requiring
9 no further testing on the part of the DP electronics consortium. Once they are delivered to the
10 designated institutions, they can be sent to SURF for the installation.

11 The commercial VHDCI signal cables (connecting the AMCs to the SFT chimneys) are procured
12 and tested with the SFT chimney warm flanges.

13 **1.3.4 Charge Readout Electronics**

14 The production of the AMC cards for the charge readout as well as the WR-MCH slave cards
15 for synchronization is currently shared between four institutions (IPNL, KEK, NITKC, IU). The
16 cards ordered and delivered to each respective institution are subjected to quality assurance tests
17 agreed upon by all participants.

18 **1.3.5 Light Readout Electronics**

19 The production of the Light Read Out AMC cards is currently envisaged to be made in the same
20 manner as the cards for ProtoDUNE Dual-Phase since the number of cards to be produced, and
21 channels to test, is small. The electronic components will be purchased, to required specifications,
22 for the production of the card. The project will be managed by a qualified engineer, and followed
23 by a specialist in Quality assurance.

24 The produced cards will be first delivered to the home institutes for testing before being shipped
25 to the DUNE far site. Basic quality tests will be made upon delivery to ensure conformity of
26 production; including visual inspection and electrical testing.

27 A series of tests will be performed on each card to ensure their correct fonctionnement and evaluate
28 their performance. Measurements will include; linearity measurements (DNL and INL) of each
29 ADC channel, and tests of the linearity of response of the ASIC. The level of cross-talk on the
30 ASIC must also be quantified.

31 A dedicated single channel setup, with PMT (Hamamatsu R5912-02-mod), and identical cabling

- 1 and splitter, can be used to characterise the expected noise level of each channel, and response to
- 2 single photoelectrons up to saturation.
- 3 Multiple cards will be operated in a uTCA crate with the DUNE DAQ.
- 4 After shipping and installation on-site, a small series of tests will be performed with a pulse
- 5 generator to verify the good working condition of the cards. Noise level measurements will also be
- 6 made as part of the integration effort.

7 1.4 Interfaces

8 The DP TPC electronics system has interfaces to several other systems. The system must read
 9 the charge and light signals from the detector module and thus needs to interface to CRP and the
 10 photo-detection systems. The digitized data must in turn be transmitted to DAQ via the optical
 11 links in each uTCA crate. The SFT chimney need to be integrated in the cryostat structure and
 12 connected to the cryogenic/gas system. The management of the low-voltage power supplies for the
 13 FE analog electronics and uTCA crates as well as the monitoring of various sensors in the SFT
 14 chimneys have to be part of the slow control. Table 1.7 provides the full list of all the relevant
 15 interface documents and only some of the principal points are summarized here.

Table 1.7: Interface documents relevant to DP electronics system

FD interface document	DUNE docdb
DP TPC Electronics to DP CRP	6751
DP TPC Electronics to DP Photon Detector	6772
DP TPC Electronics to Joint DAQ	6778
DP TPC Electronics to Joint CISC	6784
Facility Interfaces to DP TPC Electronics	6982
Installation Interfaces to DP TPC Electronics	7009
Integration Facility to DP TPC Electronics	7036
Calibration to DP TPC Electronics	7063
DUNE Physics to DP TPC Electronics	7090
Software and Computing to DP TPC Electronics	7117

16 1.4.1 CRP and Photon Detection System

17 The cold flange of the SFT chimneys forms the interface between the CRP and the TPC electronics
 18 systems. On the side facing the cryostat the flange hosts 20 68 pin connectors (KEL 8930E-068-
 19 178MS-F) for plugging the flat cables from the CRP. These are 68 channel twisted pair flat cables
 20 each carrying signals from 32 anode strips and are part of the CRP system. Each analog FE card
 21 reads 64 anode strips implying receiving signals from two KEL connectors. The order in which

1 the cables are connected into cold flange determines the mapping of the electronic channels to
 2 the physical location of the strips on the CRP and should be coordinated carefully with the CRP
 3 consortium. As an illustration, Figure 1.15 shows some images of the cold flange interface from
 4 the LArProto detector.

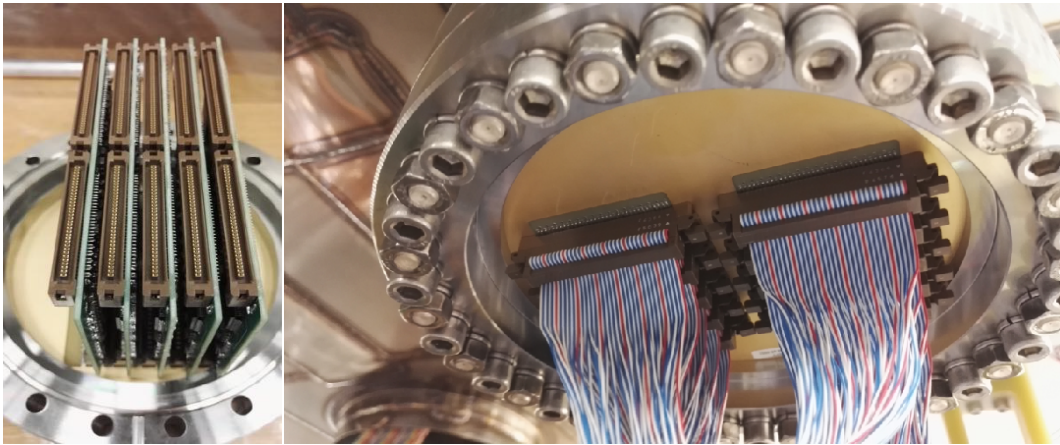


Figure 1.15: Images of LArProto SFT cold flange interface with the FE cards inserted (right) and signal cables from CRP connected (left). The LArProto SFT chimneys read only 320 channels thus requiring 5 FE cards

5 The light readout electronics is designed for negative polarity PMT signals, with the amplitude
 6 of single photoelectrons on the input of the card between 1 and 10 mV. Typically assuming a
 7 PMT gain of 1×10^6 (no accounting for attenuation of the signals), the CatiROC ASIC can measure
 8 a range of 1 to 400 photoelectrons (160 fC to 70 pC), the ADC will sample from 1 mV to 1 V
 9 corresponding to 1 to 1000 photoelectrons, including the time response of the scintillator the range
 10 can increase to ~ 6000 . Increasing the gain of the PMT to 1×10^7 , lowers the upper values by a
 11 factor of 10.

12 The internal noise level of the CatiROC is below 0.1 mV. The objective for the noise level of
 13 the ADC is for each channel to have the RMS noise level greater than 0.5 LSB, aiming for 1 LSB
 14 0.1 mV.

15 1.4.2 DAQ System

16 The hardware interface between DP-Electronics and DAQ has two components. The first interface
 17 is the 10 Gbit/s optical fibers for data transfer between the uTCA crates and the network interface
 18 of the DAQ system. The second one is a 1 Gbit/s optical fiber that connects the DAQ White
 19 Rabbit Grand Master switch to the DP electronics timing system.

20 In the baseline design a given DP detector module would have 245 10 Gbit/s optical links for
 21 streaming the digitized data to DAQ from the charge readout (240 links) and light light readout (5
 22 links) electronics housed in uTCA crates on top of the cryostat structure. In the current specifica-
 23 tions, the fibers are multimode OM3 fibers¹ with LC-LC connectors suitable for the transmission

¹<http://shop.fiber24.net/index.php/en/FO-Patch-Cable-OM3-Multi-mode-50-125-m-Duplex-LC-PC-LC-PC/c-OM3->

1 over distances of up to 300 m. They are provided by the DAQ consortium. On the side of the
 2 uTCA crate, the fibers are connected to an optical transceiver in the MCH² (two SFP+ (XAUI)
 3 links). On the DAQ, they go to the Level 1 (LV1) machines of the trigger farm, or switches,
 4 depending on the network topology adopted in the DAQ system design.

5 The 1 Gbit/s link going from the White Rabbit Grand Master to the DP-electronics time dis-
 6 tribution network serves to provide the synchronization to the reference clock common for the
 7 entire FD and derived from a GPSDO (GPS-Disciplined Oscillator) clock unit installed on the
 8 surface. The clock information is distributed to the WR-MCH slave module in each uTCA crate
 9 via a set of White Rabbit switches. These switches and the interconnecting 1 Gbit/s fibers form
 10 the timing sub-system of the DP electronics system and are included in the design of the latter.
 11 The White Rabbit synchronization protocol includes the automatic and continuous calibration of
 12 the propagation delays between the master and the connected slaves. This allows maintaining
 13 the overall synchronization between different nodes at sub-ns level. The Grand Master could be
 14 possibly located

- 15 • On surface near to GPSDO. In this case, a single fiber connects it to the DP timing system
 16 underground. The incurred latency due to the necessary fiber length to deliver the timing
 17 signals underground is automatically taken into account by the system.
- 18 • Underground in CUC. In such case, the calibration of the propagation delays between
 19 GPSDO and the Grand Master would be performed manually and the timing correction
 20 would need be applied to the data afterward.

21 The design of the TPC electronics assumes that the data are streamed continuously via the
 22 10 Gbit/s links to the DAQ system, where they are buffered until a trigger decision could be
 23 made. The triggers are to be issued by processing the buffered data in some suitable sliding time
 24 window on the trigger farm machines. The depth of the window may go up to 10 s as needed for
 25 the definition of the Supernova triggered events. The triggers determine if the data contained in
 26 the buffers are to be written on disk.

27 The software interface between DAQ and the electronics systems includes the tools dealing with
 28 the data transmission and buffering: data formatting in UDP packets, compression/decompression,
 29 and exchange of the control packets.

30 1.4.3 Cryostat and Cryogenics

31 The interface point between the cryostat and the DP electronics system is the cryostat penetrations
 32 where the SFT chimneys are to be installed. Each penetration should accommodate the chimney
 33 whose external diameter is 254 mm. Each chimney has a CF-273 flange welded to its outer structure
 34 (see Figure 1.16). After the chimney is inserted, this flange is in contact with the corresponding
 35 flange on the crossing (or penetration) pipe embedded in the cryostat structure to which it is

DUPLEX-1TO1/a-FOPC-F2-O3-DX-LCU-LCU

²<http://www.nateurope.com/products/NAT-MCH.html>

- 1 eventually fastened. In order to avoid any leaks at this interface a CF-273 copper gasket is used
 2 to ensure the vacuum tightness.

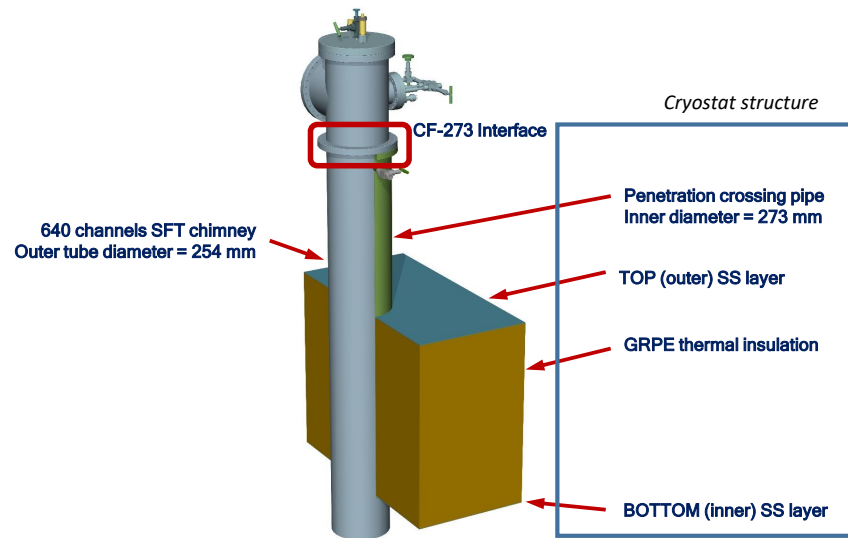


Figure 1.16: Details of SFT chimney interface to the cryostat structure

fig:dpe1

- 3 Each chimney contains a heat exchanger copper coil cooled with a liquid argon. There are two
 4 (inlet/outlet) stainless steel pipe connections with 10 mm (12 mm) inner (outer) diameter that
 5 need to be branched to the respective system for the LAr delivery and re-circulation. In addition,
 6 there is a connection for nitrogen gas line with the same pipe dimensions as those for the LAr
 7 cooling, which is used for filling the chimney after it is closed following the installation of the FE
 8 electronics. The nitrogen line is also required for flushing the chimney in the case of an access to
 9 the FE cards after the detector module is cooled for the operation.

- 10 The uTCA crates for charge readout need to be installed within a short <0.5 m distance from the
 11 SFT chimneys on top of the cryostat roof. The five uTCA crates for the light readout are also
 12 placed on the roof of the cryostat at optimal locations defined by the routing of the PMT signal
 13 cables. The required volume to accommodate the crates is roughly $60 \times 50 \times 40$ cm³.

14 1.4.4 Slow Control System

- 15 The integration with the slow control of the low voltage power supply system for the FE cards and
 16 uTCA crates is required to enable the remote management and monitoring (current consumption
 17 by ASICs, set voltage, etc.). In addition, the SFT chimneys contains several sensors that need to
 18 be monitored. These include a pressure transducer that measures the pressure inside the chimney
 19 and at least two temperature probes (PT1000) that monitor the gas temperature inside near the
 20 cold flange at the bottom and close to the warm flange at the top.

1.5 Installation, Integration and Commissioning

The installation of the TPC electronics systems proceeds in several stages. In order to cable the CRPs to the SFT chimneys, these have to be installed first prior to the start of the CRP installation inside the cryostat. After the chimneys are installed the FE cards could be mounted on the blades and inserted. The installation of the digital electronics and uTCA crates should, however, be postponed until all of the heavy work finishes on top of the cryostat in order to ensure that the fragile components (e.g., optical fibers) are not accidentally damaged due to movement of material and large traffic of personnel. Once the uTCA crates are installed and all the digital cards are inserted, the relevant AMCs are cabled to the warm flanges of the SFTs for the charge readout and are connected to the PMT signal cables for the light readout. Finally to complete the installation and integrate the system with the DAQ, the 10 Gbit/s and 1 Gbit/s optical links to the DAQ and WR timing network are connected. At this stage the full system is ready for commissioning.

1.5.1 Transport and Handling

The SFT chimneys are 2350mm long objects with the weight of 180kg. They are shipped in wooden crates with approximate dimensions of $2.5 \times 0.5 \times 0.5 \text{ m}^3$. Once on site the crates are moved underground and placed on the roof of the cryostat by the UIT. The personnel from the DP electronics consortium then proceeds to unpack the crates and install the SFT chimneys. The chimneys are delivered with the cold and warm flanges already mounted and after they have been tested for leaks by one or several participating institutions.

The boxes containing the electronic cards and uTCA crates are handled by DP electronics consortium personnel. These are foreseen to be light and could be easily carried.

1.5.2 SFT Chimneys

The installation of the SFT chimneys requires a compact gantry crane with the supports movable along the length of the cryostat. The crane itself moves along the transverse direction. The crates containing the SFT chimneys are placed along the edges of the cryostat roof. An unpacked chimney is hoisted and transported to its respective penetration crossing pipe for installation. Once in place, the chimney is fastened to the flange on the crossing pipe. The length of each chimney is about 2.4m. Enough overhead room should therefore be foreseen to allow to freely move the chimney with the crane along the direction transverse to the beam axis.

In parallel with the chimney installation, the FE cards are unpacked and mounted on the blades. This work is performed on the roof of the cryostat to avoid repackaging the blades after the assembly in order to bring them on top of the cryostat. With SFT chimneys secured in the cryostat structure, the blades with mounted FE cards can be inserted and the chimney can be sealed. At this stage, the connections with the pipes for the liquid argon and gas nitrogen delivery could also

- 1 be made, if these latter have already been installed. The pressure probes and temperature sensors
- 2 can be connected to the slow control system.

3 **1.5.3 Digital uTCA crates**

- 4 The installation of the uTCA crates with the digital electronics should happen in the final stage of
- 5 the detector installation to avoid damaging the fragile equipment. The crates are placed in their
- 6 designated positions on the cryostat and connected to the power distribution network. The AMC
- 7 cards and WR-MCH modules are inserted in their slots. The VHDCI cables are then attached
- 8 connecting the CRO AMCs to the warm flange interface of the SFT chimneys. The fibers from
- 9 the timing system are connected to WR-MCH.

10 **1.5.4 Integration within DAQ**

- 11 The integration of the DP TPC electronics with the DAQ system requires connecting the 10 Gbit/s
- 12 fiber links to each of 245 uTCA crates. The connection of the timing system to the synchronization
- 13 Grand Master is done via a single 1 Gbit/s fiber link.

- 14 The necessary software for the DAQ to read and decode the data packets sent by each uTCA crate
- 15 would also be provided.

16 **1.5.5 Integration with Photon Detection System**

- 17 The cables carrying the PMT signals from the splitter boxes need to be connected to the light
- 18 readout analog electronics in each uTCA crate. The position of the crates should be optimized with
- 19 respect to the layout of PMT cables. In addition, the calibration system of the Photon Detection
- 20 System has to be connected to specified inputs on the cards.

21 **1.5.6 Comissioning**

- 22 The SFT chimneys are commissioned as a first step. The chimneys are evacuated and then filled
- 23 with nitrogen gas at slight overpressure with respect to the atmospheric pressure.

- 24 The electronics system can be commissioned after the installation of the uTCA and the timing
- 25 system is complete. The functionality of the full DAQ system is not strictly required at this stage.
- 26 The data from each crate could be read with a portable computer connected to the crate MCH
- 27 10 Gbit/s or 1 Gbit/s interface. By pulsing the CRP strips the non-functioning channels could be
- 28 identified. The data quality would also be examined to ensure the correct functioning of the digital
- 29 electronics and the temporal alignment of the data segments.

1.6 Risks and Vulnerabilities

The design of the DP electronics system takes into account several risks factors:

- **Obsolescence of electronic components over the period of experiment:** allocation of enough spares (preferably complete cards instead of components) should be sufficient to address this issue.
- **Modification to FE electronics due to evolution in design of photon detectors:** strict and timely follow-up of the FE requirements from the DP photon system is required.
- **Damage to electronics due HV discharges or other reasons:** the FE cards should include suitable protection components. The TVS diodes used in the current design have been sufficient to protect the electronics in LArProto detector. In addition, the cards are accessible and could be replaced if damaged.
- **Overpressure in the SFT chimneys:** the SFT chimneys are equipped with safety valves that vent the excess gas in case of the sudden pressure rise. The overpressure threshold should be set low enough such that no significant damage could happen to the flanges.
- **Leak of nitrogen inside the detector via cold flange:** the chimney volume would be filled with argon gas instead of nitrogen.
- **Mechanical problems with FE card extraction due to overhead clearance:** in case of insufficient overhead space it would not be possible to extract the blades from the SFT chimneys. This is addressed by making the requirement for LBNF to ensure there is always enough clearance around the chimneys.
- **Data flow increase due to inefficient compression caused by higher noise:** currently there is a factor of 5 margin in the available bandwidth with 10 Gbit/s MCH.
- **Damage to uTCA crates due to presence of water on the roof of the cryostat:** requirement to LBNF to ensure that the cryostat surface remains dry.
- **Problems with the ventilation system of the uTCA crates due to bad air quality:** normal conditions similar to any industrial environment at CERN/FNAL should be sufficient to ensure that crates function properly. Liberation of large quantities of dust due to activities in the mine are to be avoided.

1.7 Organization and Management

1.7.1 Dual-Phase TPC Electronics Consortium Organization

The Dual-Phase TPC electronics consortium actually consists of seven participating institutions from France (3), Japan (3), and USA (1). The consortium leader is Dario Autiero (IPNL, France) and the technical leader is Takuya Hasegawa (KEK, Japan). The composition of the consortium along with the information for each institutional representative is provided in Table 1.8.

Table 1.8: DP TPC electronics consortium current participants

Institution	Investigator	Contact
France: APC	Thomas Patzak	thomas.patzak@cern.ch
France: IPNL	Dario Autiero	autiero@cern.ch
France: LAPP	Dominique Duchesneau	duchesneau@lapp.in2p3.fr
Japan: Iwate University	Shinya Narita	narita@iwate-u.ac.jp
Japan: KEK	Takuya Hasegawa	takuya.hasegawa@kek
Japan: NITKC	Seiji Kasai	kasai@kure-nct.ac.jp
USA: Southern Methodist University	Thomas Coan	coan@smu.edu

1.7.2 Planning Assumptions

The present design of the DP TPC electronics system mostly relies on the elements that have already been developed and tested in LArProto detector. Commissioning of the ProtoDUNE-DP towards the end of the year should provide some additional information, but is not expected to affect the design of principal components. Some additional improvements related to the increase in the channel density supported by AMCs could be envisioned for the purpose of further reduction in costs.

1.7.3 WBS and Responsibilities

The description of the WBS including the assignments of the responsible institutions is documented in DUNE-doc-5594 and provided in addendum.

1.7.4 High-level Cost and Schedule

The detailed cost model has been developed based on the scaling of the costs for the electronics system of ProtoDUNE-DP. It is provided in addendum. Table 1.9 shows an extract from the international project schedule pertaining to the technical activities of the consortium.

Table 1.9: DP TPC electronics consortium schedule

Technical activity	Days	Start date	End date
Preparation of costing for Technical Proposal	20	02/26/18	03/23/18
Initial Development of Installation Schedule	20	02/26/18	03/23/18
Further Development of Installation Schedule	145	09/03/18	03/22/19
Installation and Commissioning of PD-DP	320	01/01/18	03/22/19
Finalization of the number of channels for light readout	20	09/03/18	09/28/18
Implementation of routing for digital cards of light readout	40	10/01/18	11/23/18
Preparation of final costing for TDR	85	11/26/18	03/22/19
Firmware development for charge readout cards	145	09/03/18	03/22/19

schedule

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16 **Team, Fermi-LAT, J-GEM, RATIR, IceCube, CAASTRO, LWA, ePESSTO,**
17 **GRAWITA, RIMAS, SKA South Africa/MeerKAT, H.E.S.S., 1M2H Team,**
18 **IKI-GW Follow-up, Fermi GBM, Pi of Sky, DWF (Deeper Wider Faster**
19 **Program), Dark Energy Survey, MASTER, AstroSat Cadmium Zinc Telluride**
20 **Imager Team, Swift, Pierre Auger, ASKAP, VINROUGE, JAGWAR, Chandra**
21 **Team at McGill University, TTU-NRAO, GROWTH, AGILE Team, MWA,**
22 **ATCA, AST3, TOROS, Pan-STARRS, NuSTAR, ATLAS Telescopes, BOOTES,**
23 **CaltechNRAO, LIGO Scientific, High Time Resolution Universe Survey, Nordic**
24 **Optical Telescope, Las Cumbres Observatory Group, TZAC Consortium,**
25 **LOFAR, IPN, DLT40, Texas Tech University, HAWC, ANTARES, KU, Dark**
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